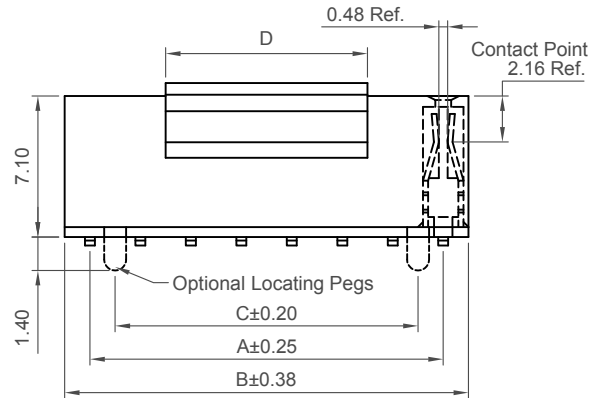
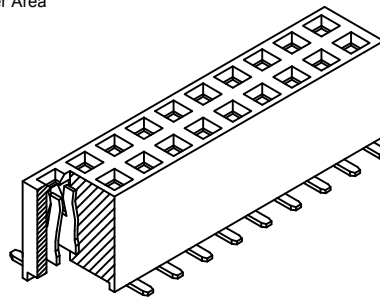
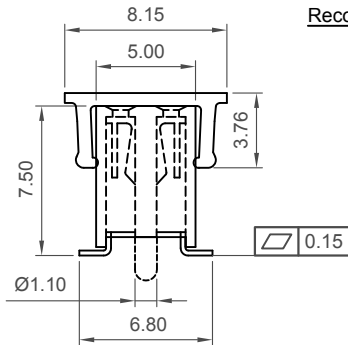


Recommended PCB Layout

▨ Solder Area



Number of Contacts	Dimensions			
	A	B	C	D
4	2.54	5.08	n/a	4.00
6	5.08	7.62	2.54	
8	7.62	10.16	5.08	
10	10.16	12.70	7.62	
12	12.70	15.24	10.16	
14	15.24	17.78	12.70	
16	17.78	20.32	15.24	
18	20.32	22.86	17.78	
20	22.86	25.40	20.32	
22	25.40	27.94	22.86	
24	27.94	30.48	25.40	
26	30.48	33.02	27.94	
28	33.02	35.56	30.48	
30	35.56	38.10	33.02	
32	38.10	40.64	35.56	
34	40.64	43.18	38.10	
36	43.18	45.72	40.64	
38	45.72	48.26	43.18	
40	48.26	50.80	45.72	
42	50.80	53.34	48.26	
44	53.34	55.88	50.80	
46	55.88	58.42	53.34	
48	58.42	60.96	55.88	
50	60.96	63.50	58.42	
52	63.50	66.04	60.96	
54	66.04	68.58	63.50	
56	68.58	71.12	66.04	
58	71.12	73.66	68.58	
60	73.66	76.20	71.12	
62	76.20	78.71	73.66	
64	78.71	81.28	76.20	
66	81.28	83.82	78.71	
68	83.82	86.36	81.28	
70	86.36	88.90	83.82	
72	88.90	91.44	86.36	
74	91.44	93.98	88.90	
76	93.98	96.52	91.44	
78	96.52	99.06	93.98	
80	99.06	101.60	96.52	

Specifications 规格

Material 物料

Insulator 绝缘体:

Standard 标准: Polyamide, Nylon 6T, UL 94V-0

Option 可选: Polymer, LCP, UL 94V-0

Contact 端子: Copper Alloy

Plating 电镀

See Ordering Grid

Electrical 电气

Current Rating 电流额定值: 3 Amp per pin

Insulator Resistance 绝缘电阻值: 1000 MΩ min.

Dielectric Withstanding 耐电压: AC 600 V

Contact Resistance 接触电阻值: 20mΩ max.

Mechanical & Environmental 机械 & 环境

Operating Temperature 工作温度: -40°C to +105°C

Soldering Process 可焊性:

Nylon 6T (Standard标准物料) -

IR Reflow 回流焊: 260°C for 10 sec.

Wave 波峰焊: 230°C for 5-10 sec.

Manual Solder 人工焊接: 350°C for 3-5 sec

LCP (Option 可选物料) -

IR Reflow 回流焊: 260°C for 10 sec.

Wave 波峰焊: 250°C for 5-10 sec.

Manual Solder 人工焊接: 350°C for 3-5 sec

Mates With 配套之公头 (Subject to pin length 在端子长度适合的条件下)

BG025 BG040 BG041 BG045 BG050

BG065 BG066 BG070 BG085

Ordering Grid



No. of Contacts
04 to 80

Packing Options

C = Tape & Reel with Film (Standard)

B = Tape & Reel with Cap

D = Tube

E = Tube with Cap

F = Tube with Film

Insulator Material

N = Nylon 6T (Standard)

L = LCP

Contact Plating

A = Gold Flash All Over (Standard)

B = Selective Gold Flash Contact Area/Tin On Tail

C = Tin All Over

G = 10μ" Gold Contact Area/Tin On Tail

I = 30μ" Gold Contact Area/Tin On Tail

Locating Peg

0 = Without

1 = With

For bottom entry applications the locating peg option is recommended. Stringent soldering control & pin alignment are required as lead to pad misalignment could cause incorrect mating.

Part Number BG180		Product Description 2.54mm Pitch Socket Dual Row, Surface Mount, Vertical, Dual Entry	
Drawing Date 30th October 2006			
By	CC	Tolerances (Except as Noted)	Units: Metric (mm)
Detail	BG180 F PCN	Length X. ± 0.30 X.X ± 0.20 X.XX ± 0.15 X.XXX ± 0.10	Angle X° ± 5° X.X° ± 2° X.XX° ± 1° X.XXX° ± 0.5°
Revision	F2	3rd Angle Projection	
Date	27/06/17		



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Not to Scale	Drawn AJO	Sheet No. 1/1
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